


**NOTES**

1. MATERIALS:  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
2. FINISH:  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
5. PACKAGE CONFORMS TO JEDEC MO-220

**PROPRIETARY AND CONFIDENTIAL**  
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		NAME	DATE	 <b>TITLE:</b> QP-QFN20-5MM-0.65MM
		DRAWN	D. Abbe	8/16/11		
		CHECKED	S. Swen	8/16/11		
		ENG APPR.	S. Swen	8/16/11		
		MATERIAL		COMMENTS:		
		SEE NOTE 1				
		FINISH				
		SEE NOTE 2				
NEXT ASSY	USED ON			SCALE: 10:1	DWG. NO.	REV
APPLICATION		DO NOT SCALE DRAWING		<b>B</b>	<b>500421</b>	<b>A</b>
				WEIGHT:	SHEET 1 OF 1	

